

**Abstract of the Disclosure**

A semiconductor apparatus having a semiconductor substrate including an integrated circuit and an insulative base member formed on a main surface thereof. A conductive layer is formed on the main surface of the semiconductor substrate as coupled to the integrated circuit and includes an extended portion that extends onto a top surface of the base member. A sealing member is formed on the main surface of the semiconductor substrate, the conductive layer and side surfaces of the base member, whereby the extended portion of the conductive layer is exposed from the sealing member.